



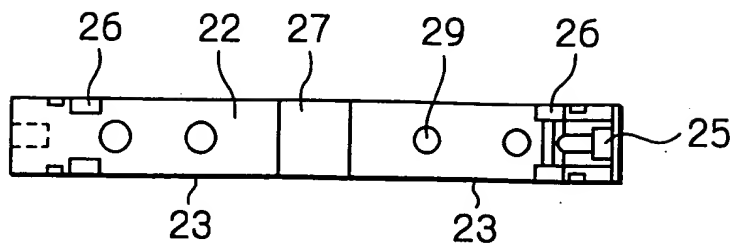
A cross-sectional view of a circular device. It features a central core labeled 27, surrounded by a thick, multi-layered ring labeled 23(22). This ring is further enclosed by a thin outer shell labeled 26. A dashed line with arrows at both ends, labeled B, passes through the center of the device. A small circular feature, labeled 25, is located on the left side of the device, within the thin outer shell. Another label 28 points to the right side of the thin outer shell.

A cross-sectional view of a semiconductor device 100. The device features a substrate 10 with a central region 22. On the left side of region 22, there is a structure 23 containing two circular elements 24. This structure is connected to a horizontal layer 25. On the right side of region 22, there is a structure 26 containing two circular elements 23. This structure is connected to a horizontal layer 28. Both horizontal layers 25 and 28 are connected to a common horizontal layer 31 at the bottom. The device is bounded by vertical walls 27 on the left and right. A cross-section line A-A is indicated on the right side, and a horizontal line G-G is indicated at the bottom.

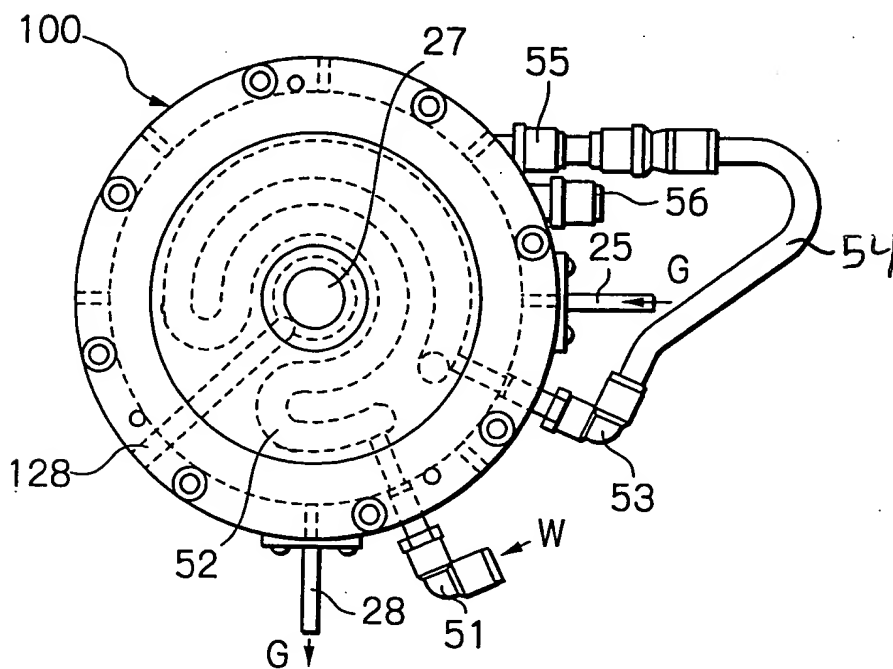


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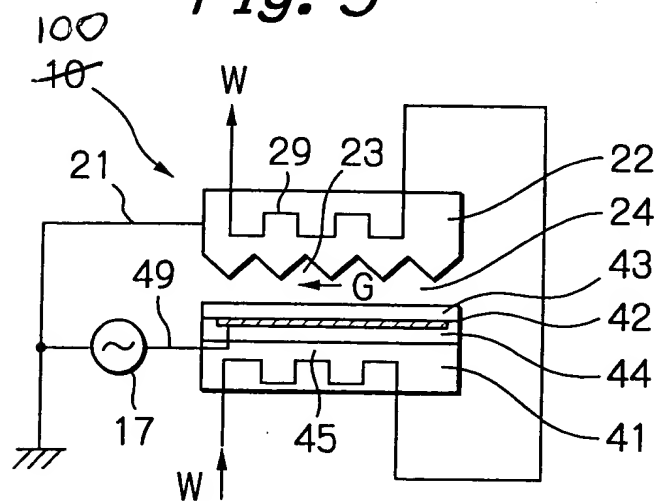
*Fig. 3*



*Fig. 4*



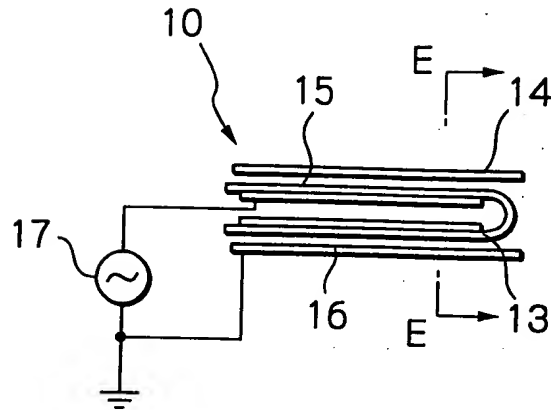
*Fig. 5*



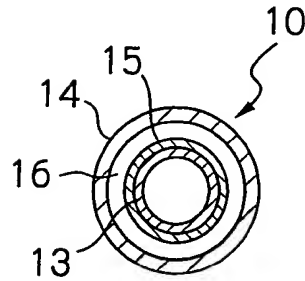


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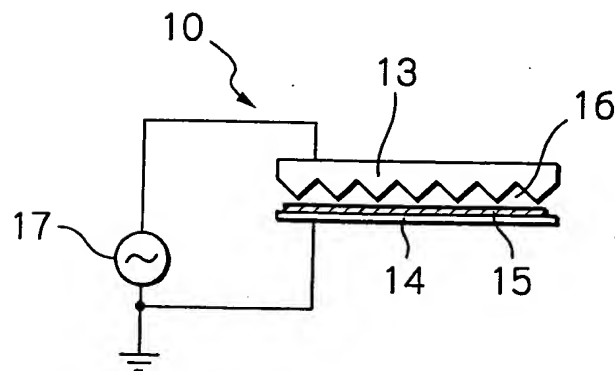
*Fig. 9* PRIOR ART



*Fig. 10* PRIOR ART



*Fig. 11* PRIOR ART





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*Fig. 12* PRIOR ART

